



Product / Process Change Notice

No.: Z200-PCN-DM201204-01-A

Date: April 1, 2012

Change Title : W25Q40/X40 "C-Series" (90nm) to replace W25Q40/X40 "B -Series" (90nm) 4Mb SpiFlash® Memories

Change Classification: Major Minor

Change item : Design Raw Material Wafer FAB Package Assembly Testing Others :

Affected Product(s) :

90nm 4Mb "B-Series" SpiFlash memories:
 W25X40BVSIG, W25X40BVSSIG, W25X40BLSNIG, W25X40BVZPIG, W25X40BLZPIG, W25X40BLUXIG,
 W25X40BLWC, W25Q40BLSNIG, W25Q40BLSSIG, W25Q40BVSSIP, Q25Q40BVWC

Description of Change(s) :

To provide function-compatible 4M devices offering improved performance, features and availability under same process technology generation.

Reason for Change(s) :

1) Improved Features and Performance (see below)

Features

- a) Up to 104MHz Clock at 3.3V
- b) Low power consumption: Active current from 4mA to 1mA
- c) Standby current from 25uA to 10uA
- d) Fully backward compatible with W25Q40B/X40B
- e) Fast Write (tpp=400uS)

Benefits

- > Better system performance and timing margin
- > Provides drop-in replacement capability for seamless transitions

Impact of Change(s) : (positive & negative)

Form: No Change

Fit: No Change

Function: No concern (No system Change is needed unless new feature, ex QPI and Software Reset, will be used.

Reliability: No concern (refer to Attachment I)

Hazardous Substances: No concern

Qualification Plan/ Results :

Based on Winbond W25Q40CL Serial Flash Reliability report, the new product meets our criteria and no quality concern (refer to Attachment I in details).

Implementation Plan :

The sample is mass-shipped after getting customer's approval.

Date Code : _____ onward Lot No.: _____ onward Implementation date: See Appendix I .

Originator:(QA Sec. Manager)

YH Cheng

Responsible:(QA Dept. Manager)

YH Cheng

Approval:(QRA Director)

Yu-Sung, Cheng

Contact for Questions & Concerns

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Customer Comments:

Note: Please sign this notice, and return to Winbond contact within 30 days. If no response is received within 30 days, this Change Request will be assumed to meet your approval.

Approval Disapproval Conditional Approval : _____.

Date: _____

Dept. name: _____

Person in charge: _____.



Table 1 The impact product list: Primary Winbond replacement part numbers for 90nm W25Q40/X40 B-Series products are listed below. These devices offer the best future availability.

Winbond Current PN (90nm B-Series)	Winbond Primary Replacement PN (90nm C-Series)
W25Q40BLSNIG	W25Q40CLSNIG
W25Q40BLSSIG	W25Q40CLSSIG
W25Q40BVSSIP	W25Q40CLSSIP
W25Q40BVWC	W25Q40CLWC

Winbond Current PN (90nm B-Series)	Winbond Primary Replacement PN (90nm C-Series)
W25X40BLSNIG	W25X40CLSNIG
W25X40BLUXIG	W25X40CLUXIG
W25X40BLZPIG	W25X40CLZPIG
W25X40BVSNIG	W25X40CLSNIG
W25X40BVZPIG	W25X40CLZPIG
W25X40BVSSIG	W25X40CLSSIG



Table 1 The impact product list: Primary Winbond replacement part numbers for 90nm W25X10/X20 B/C-Series products are listed below. These devices offer the best future availability.

Winbond Current PN (90nm B-Series)	Winbond Primary Replacement PN (90nm C-Series)	Winbond Current PN (90nm B-Series)	Winbond Primary Replacement PN (90nm C-Series)
W25X10BVSNIG	W25X10CLSNIG	W25X20BLZPIG	W25X20CLZPIG
W25X10BLSNIG	W25X10CLSNIG	W25X20BVZPIG	W25X20CLZPIG
W25X10BLZPIG	W25X10CLZPIG	W25X20BVSNIG	W25X20CLSNIG
W25X10BVZPIG	W25X10CLZPIG	W25X20BLSNIG	W25X20CLSNIG
		W25X20BLUXIG	W25X20CLUXIG